

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An optical element mounted body comprising:
an optical semiconductor element having a light-emitting/light-receiving portion and a ~~predetermined structure formed~~ projection in the vicinity of an edge and/or along a V-groove marker on a primary surface thereof; and
a substrate having a mounting surface formed with a first hollow;
wherein said optical semiconductor element is mounted junction-down on said substrate such that said ~~structure~~ projection of said optical semiconductor element and said first hollow of said substrate are positioned to oppose one another ~~face each other~~.

Claim 2 (Currently Amended): The optical element mounted body according to claim 1, wherein said ~~structure~~ V-groove marker is formed with a predetermined positional relation to said light-emitting/light-receiving portion.

Claim 3 (Currently Amended): The optical element mounted body according to claim 2, wherein said ~~structure~~ V-groove marker is used as an alignment marker when aligning said light-emitting/light-receiving portion on said substrate.

Claims 4 (Canceled).

Claim 5 (Currently Amended): The optical element mounted body according to claim 1 [[4]], wherein said first hollow receives said projection.

Claim 6 (Currently Amended): The optical element mounted body according to claim 1, ~~wherein said structure is~~ further comprising:

a second hollow extending in parallel to a light-emitting/light-receiving direction of said light-emitting/light-receiving portion which is used as an alignment marker when aligning said substrate to a package.

Claim 7 (Original): The optical element mounted body according to claim 6, wherein said second hollow is a V-groove.

Claim 8 (Original): The optical element mounted body according to claim 6, wherein said first hollow extends in parallel to a light-emitting/light-receiving direction of said light-emitting/light-receiving portion.

Claim 9 (Original): The optical element mounted body according to claim 1, wherein said substrate is made of silicon.

Claim 10 (Currently Amended): The optical element mounted body according to claim 9, wherein said first hollow includes etched walls ~~is formed by etching a part of said substrate.~~

Claim 11 (Currently Amended): The optical element mounted body according to claim 9, wherein said first hollow is not less than 10[[mm]]μm in width, and not less than 5[[mm]]μm in depth.

Claim 12 (Original): The optical element mounted body according to claim 1 [[4]], wherein said projection is composed of a semiconductor.

Claim 13 (Currently Amended): The optical element mounted body according to claim 12, wherein said projection is comprised of ~~is deposited by~~ crystal growth.

Claim 14 (Currently Amended): An optical module comprising:
an optical semiconductor element having a light-emitting/light-receiving portion and a ~~predetermined structure formed~~ projection generated in the vicinity of an edge and/or along a V-groove marker on a primary surface thereof;
a substrate having a mounting surface;
an optical component optically coupled to said optical semiconductor element; and
a package housing said optical semiconductor element and said substrate;
wherein said substrate has a first hollow formed on said mounting surface, and
wherein said optical semiconductor element is mounted junction-down on said substrate such that said ~~structure~~ projection of said optical semiconductor element and said first hollow of said substrate are positioned to oppose one another ~~face each other~~.

Claim 15 (Currently Amended): The optical module according to claim 14, wherein said projection has ~~structure is formed with~~ a predetermined positional relation to said light-emitting/light-receiving portion.

Claim 16 (Canceled).

Claim 17 (Currently Amended): The optical module according to claim 14 [[16]], wherein said first hollow receives said projection.

Claim 18 (Currently Amended): The optical module according to claim 14, wherein said substrate is made of silicon, ~~and wherein said first hollow is formed by etching a part of said substrate.~~